

## Part Number: XZVG55W-3

3.2x1.6mm SMD CHIP LED LAMP

# Features

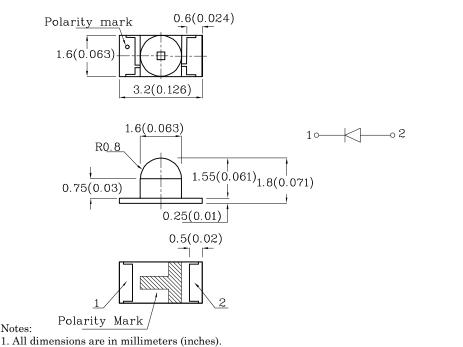
- $\bullet$  Ideal for indication light on hand held products
- $\bullet$  Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

# Package Schematics



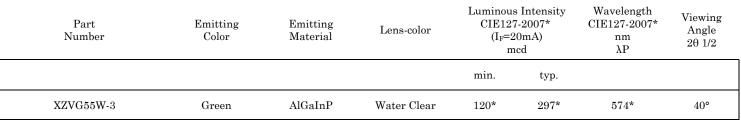
2. Tolerance is  $\pm 0.2(0.008")$  unless otherwise noted.

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		Green (AlGaInP)	Unit
Reverse Voltage	$V_{\mathrm{R}}$	5	V
Forward Current	$\mathbf{I}_{\mathbf{F}}$	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA
Power Dissipation	PD	75	mW
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C
Storage Temperature	Tstg	$-40 \sim +85$	10

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T <sub>A</sub> =25°C)		Green (AlGaInP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2.1	V
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	2.5	V
Reverse Current (Max.) $(V_R=5V)$	$I_R$	10	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I <sub>F</sub> =20mA)	λP	574*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =20mA)	λD	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	$ riangle\lambda$	20	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	15	$_{\rm pF}$

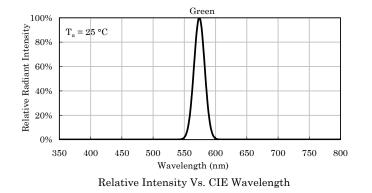


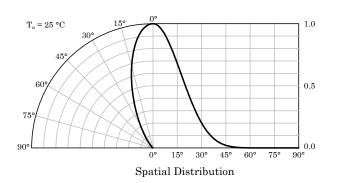
\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

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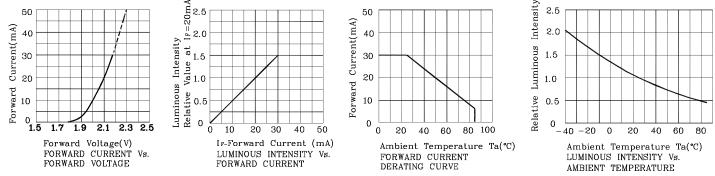
XDSA8110 V7-Z Layout: Maggie L.



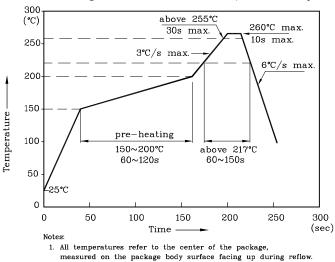








### LED is recommended for reflow soldering and soldering profile is shown below.

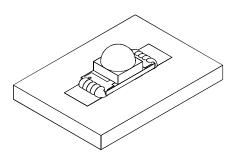


Reflow Soldering Profile for SMD Products (Pb-Free Components)

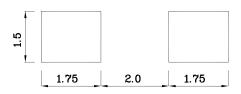
Do not apply any stress to the LED during high temperature conditions.
Maximum number of soldering passes: 2



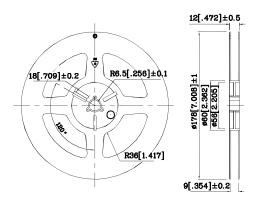
✤ The device has a single mounting surface. The device must be mounted according to the specifications.



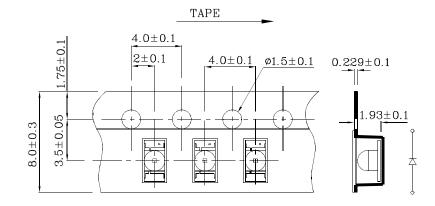
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



### Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

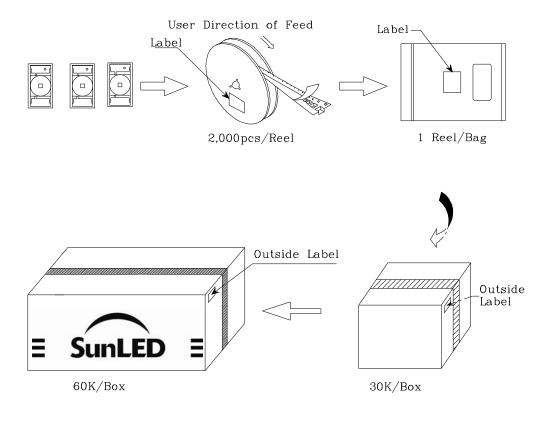
3. Forward Voltage: +/-0.1V  $\,$ 

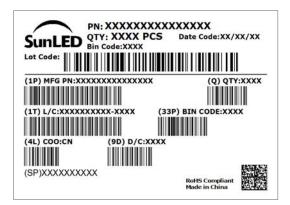
Note: Accuracy may depend on the sorting parameters.

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#### PACKING & LABEL SPECIFICATIONS





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